

Dual N & P-Channel PowerTrench® MOSFET

N-Channel: 40V, 30A, 24mΩ P-Channel: -40V, -30A, 30mΩ

Features

n-chann

V_{DS} (V) = 40V, I_D = 30A (V_{GS} =10V)

$R_{DS(ON)} < 24\text{m}\Omega$ (V_{GS} =10V)

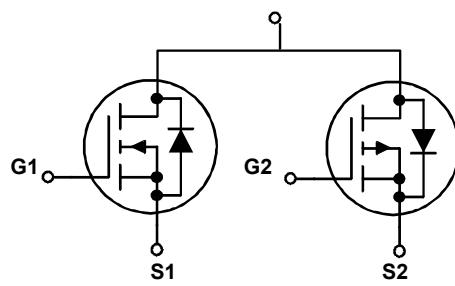
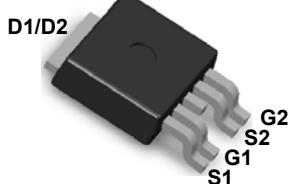
$R_{DS(ON)} < 30\text{m}\Omega$ (V_{GS} =4.5V)

p-channel

V_{DS} (V) = -40V, I_D = -30A (V_{GS} =-10V)

$R_{DS(ON)} < 30\text{m}\Omega$ (V_{GS} = -10V)

$R_{DS(ON)} < 36\text{m}\Omega$ (V_{GS} = -4.5V)



Dual DPAK 4L

N-Channel

P-Channel

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$, unless otherwise noted)					
PARAMETER		SYMBOL	N-CHANNEL	P-CHANNEL	UNIT
Drain-Source Voltage		V_{DS}	40	- 40	V
Gate-Source Voltage		V_{GS}		± 20	
Continuous Drain Current ^a	$T_C = 25^\circ\text{C}$	I_D	30	-30	A
	$T_C = 125^\circ\text{C}$		35	-35	
Continuous Source Current (Diode Conduction) ^a		I_S	30	-30	
Pulsed Drain Current ^b		I_{DM}	150	-150	
Single Pulse Avalanche Current	$L = 0.1 \text{ mH}$	I_{AS}	30	-30	mA
Single Pulse Avalanche Energy		E_{AS}	245	245	
Maximum Power Dissipation ^b	$T_C = 25^\circ\text{C}$	P_D	108	108	W
	$T_C = 125^\circ\text{C}$		32	32	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to + 175		°C
Soldering Recommendations (Peak Temperature)			260		

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	N-CHANNEL	P-CHANNEL	UNIT
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	85	85	°C/W
Junction-to-Case (Drain)		R_{thJC}	3.1	3.1	

Notes

a. Package limited.

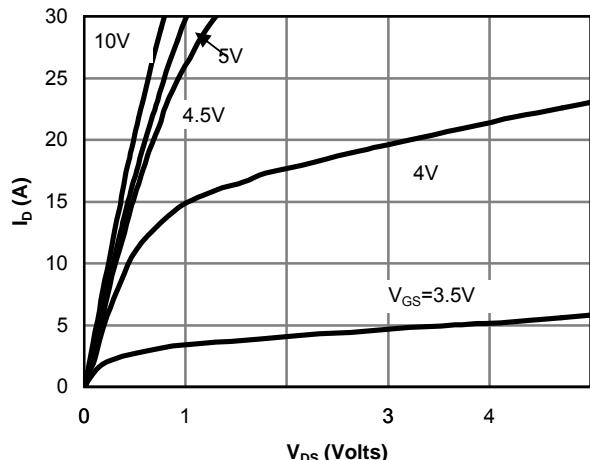
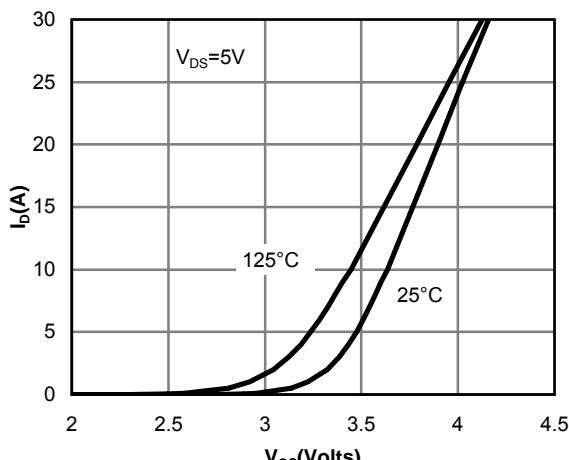
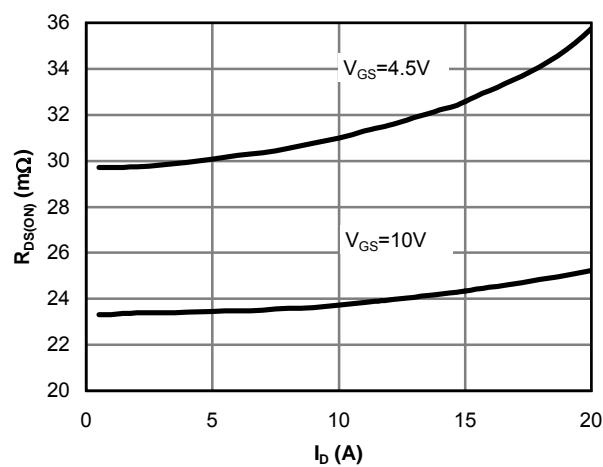
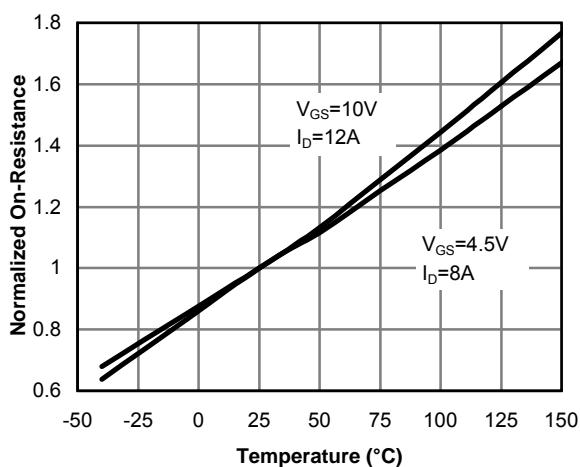
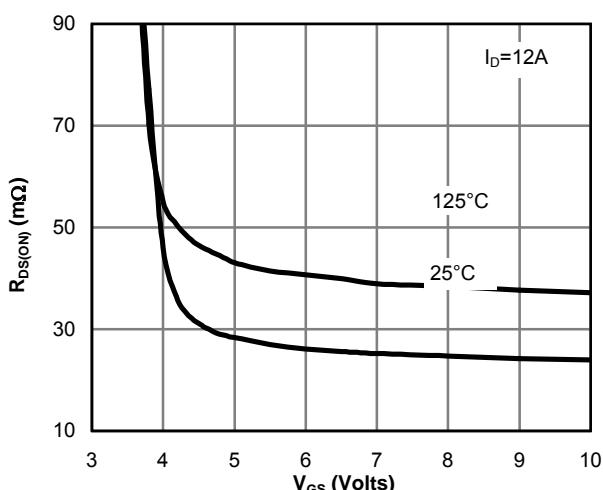
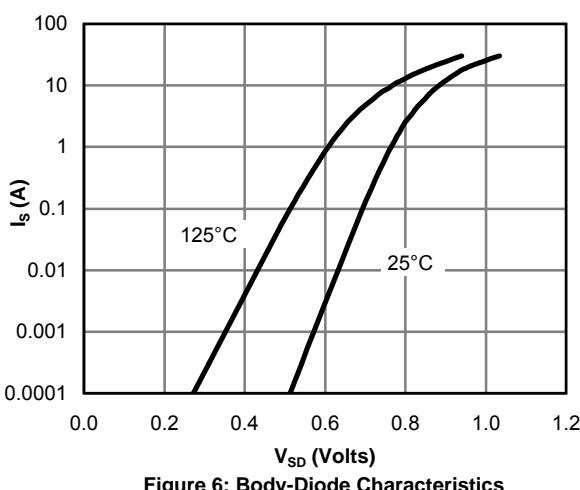
b. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.

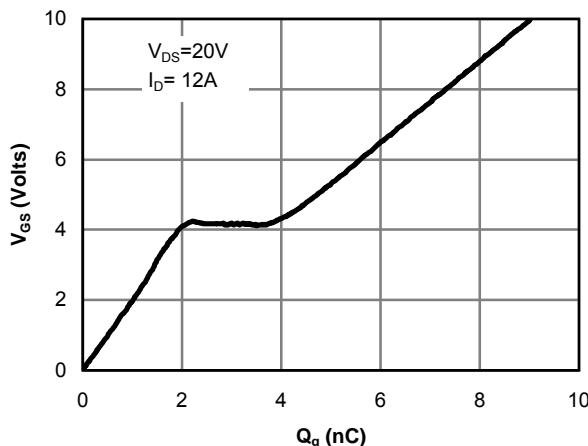
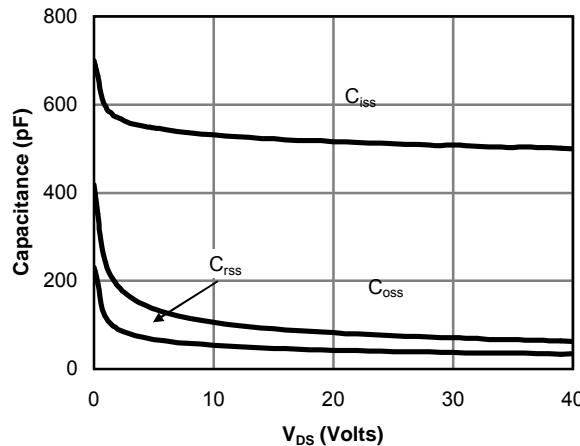
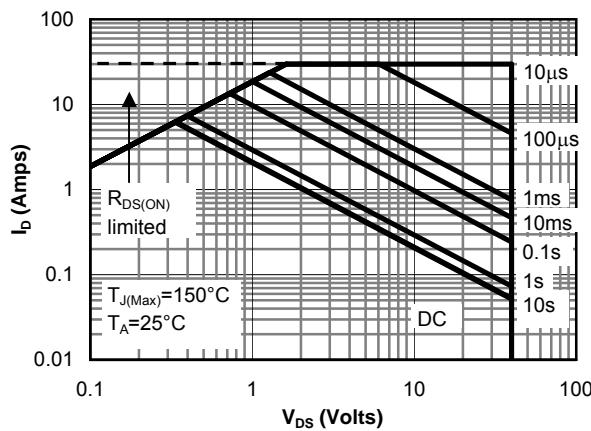
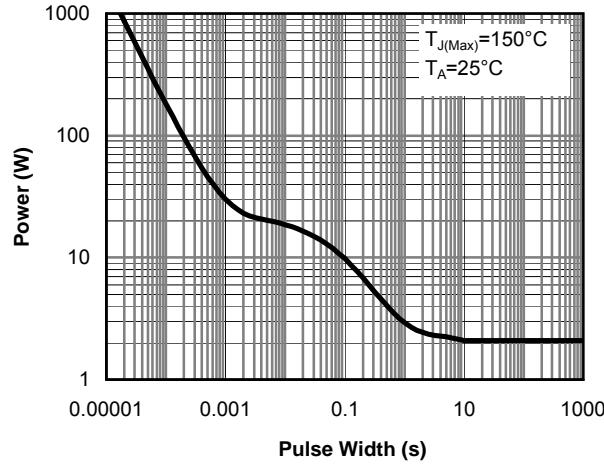
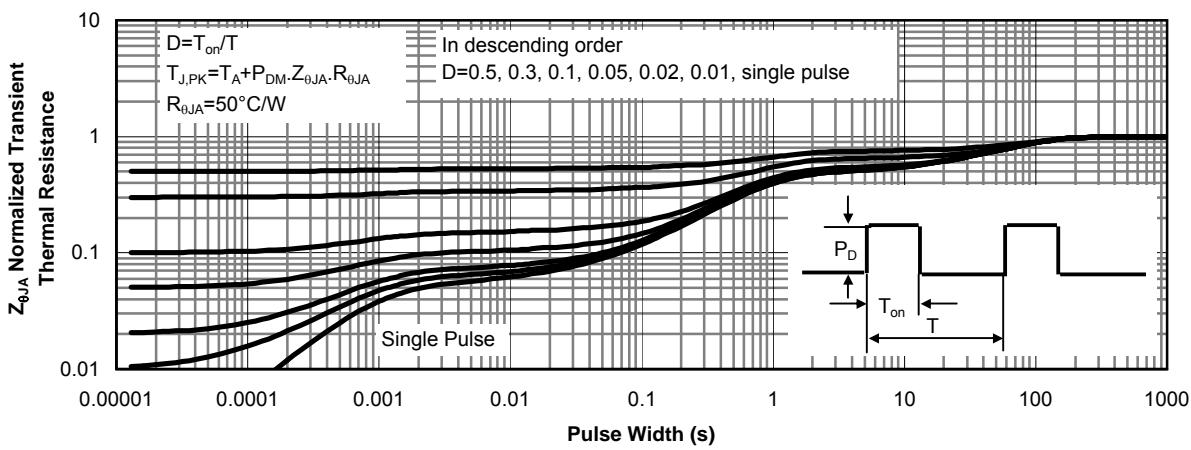
c. When mounted on 1" square PCB (FR4 material).

d. Parametric verification ongoing.

N Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

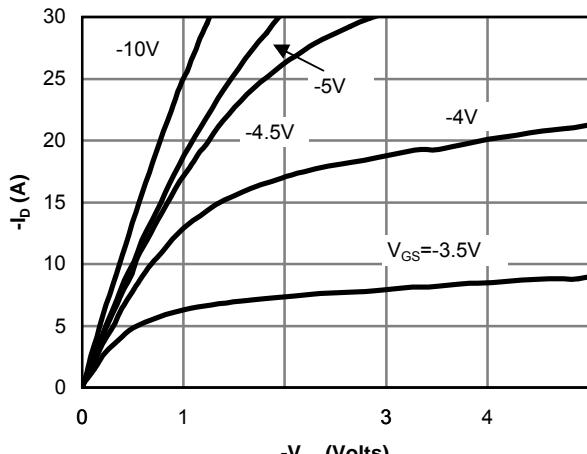
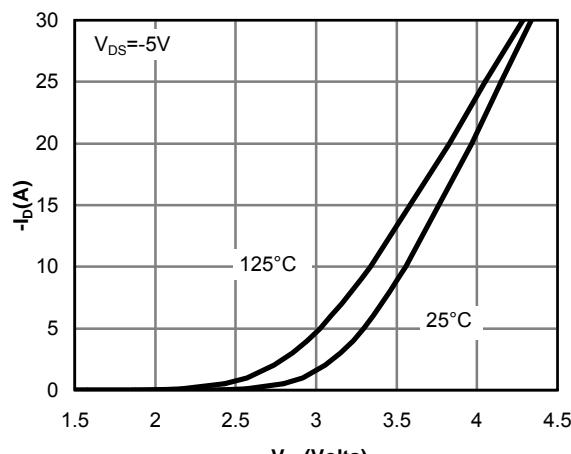
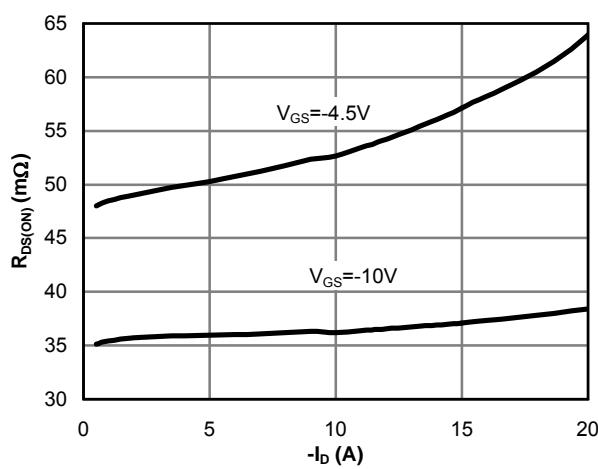
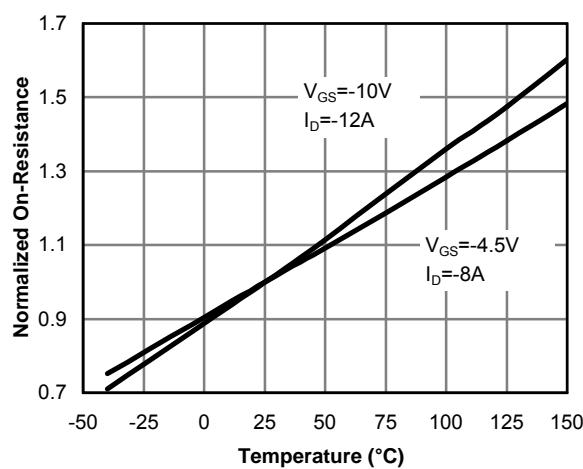
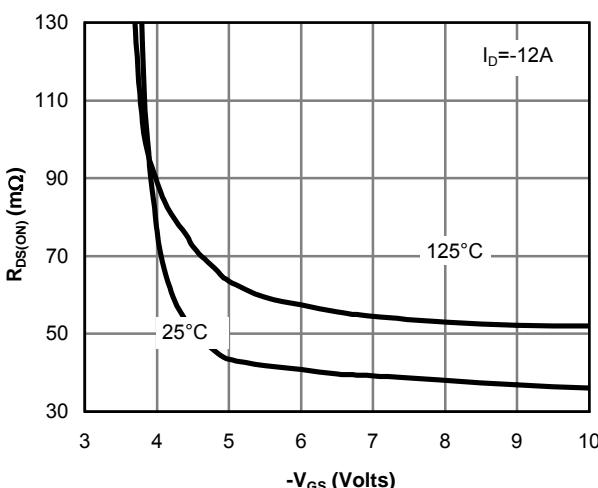
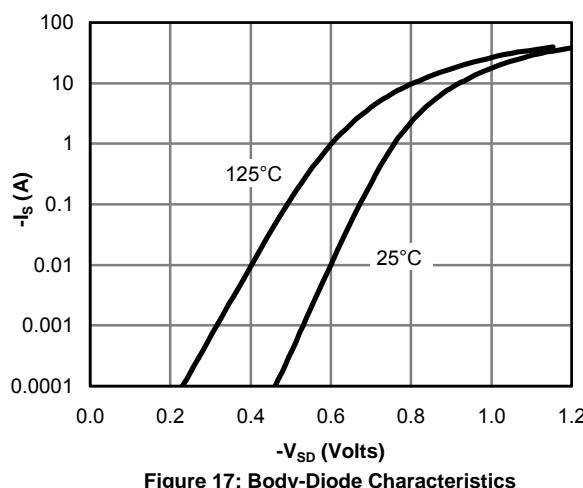
Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	40			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=40\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			± 100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.7	2.5	3	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=10\text{V}, V_{DS}=5\text{V}$	30			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=30\text{A}$		24		$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=20\text{A}$		30		
g_{FS}	Forward Transconductance	$V_{DS}=10\text{V}, I_D=30\text{A}$		23		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.76	1	V
I_S	Maximum Body-Diode Continuous Current				2	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=20\text{V}, f=1\text{MHz}$		1000	1500	pF
C_{oss}	Output Capacitance			150		pF
C_{rss}	Reverse Transfer Capacitance			100		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		1.5	3.5	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=20\text{V}, I_D=30\text{A}$		8.3	10.8	nC
Q_{gs}	Gate Source Charge			2.3		nC
Q_{gd}	Gate Drain Charge			1.6		nC
$t_{\text{D(on)}}$	Turn-On DelayTime	$V_{GS}=10\text{V}, V_{DS}=20\text{V}, R_L=1.4\Omega, R_{\text{GEN}}=3\Omega$		6.4		ns
t_r	Turn-On Rise Time			3.6		ns
$t_{\text{D(off)}}$	Turn-Off DelayTime			16.2		ns
t_f	Turn-Off Fall Time			6.6		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=12\text{A}, dI/dt=100\text{A}/\mu\text{s}$		18	24	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=12\text{A}, dI/dt=100\text{A}/\mu\text{s}$		10		nC

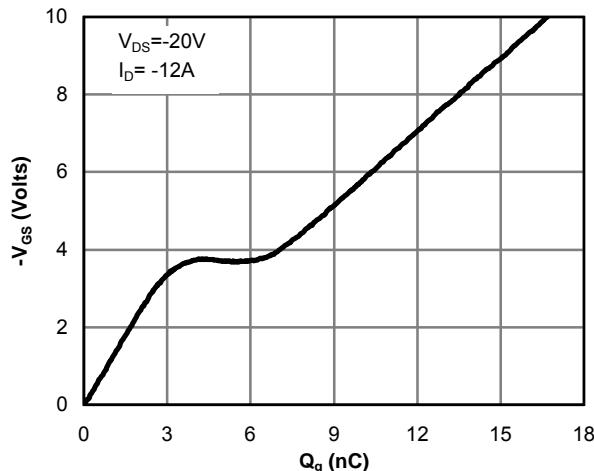
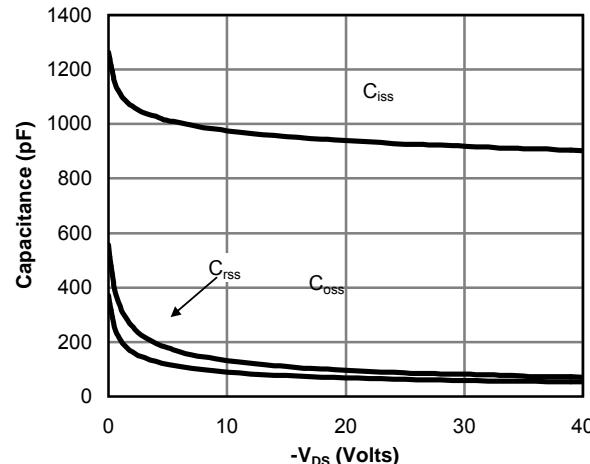
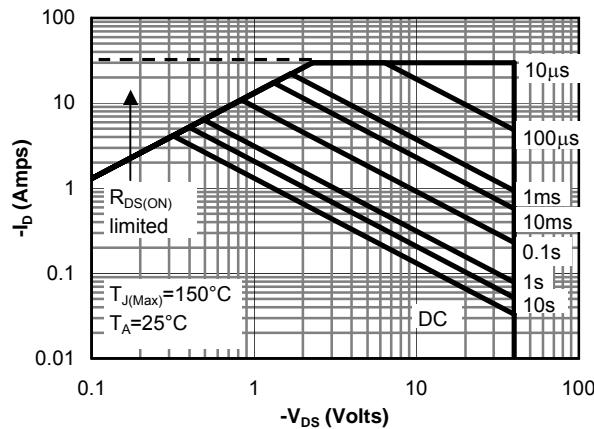
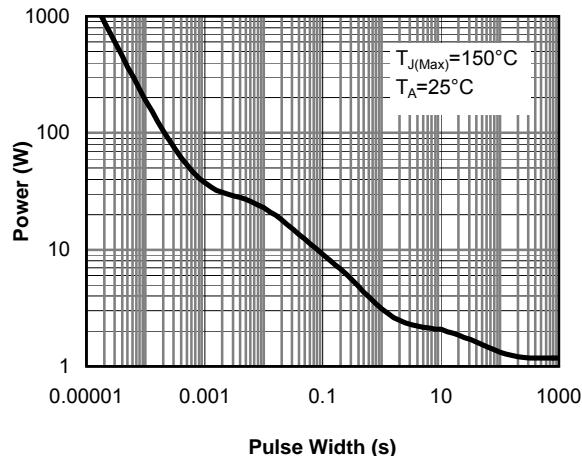
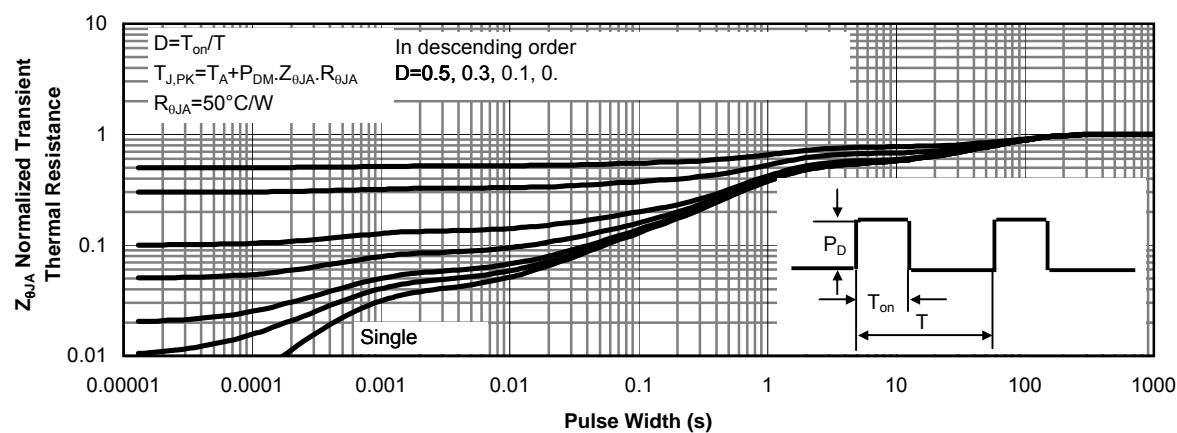
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: N-CHANNEL

Fig 1: On-Region Characteristics

Figure 2: Transfer Characteristics

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

Figure 4: On-Resistance vs. Junction Temperature

Figure 5: On-Resistance vs. Gate-Source Voltage

Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: N-CHANNEL

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

Figure 11: Normalized Maximum Transient Thermal Impedance

P-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D = -250\mu\text{A}, V_{GS}=0\text{V}$	-40			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -40\text{V}, V_{GS}=0\text{V}$	$T_J=55^\circ\text{C}$	-1	-5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}= \pm 20\text{V}$			± 100	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D = -250\mu\text{A}$	-1.7	-2	-3	V
$I_{D(\text{ON})}$	On state drain current	$V_{GS} = -10\text{V}, V_{DS} = -5\text{V}$	-30			A
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS} = -10\text{V}, I_D = -30\text{A}$		30		$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -20\text{A}$		36		
g_{FS}	Forward Transconductance	$V_{DS} = -10\text{V}, I_D = -30\text{A}$		22		S
V_{SD}	Diode Forward Voltage	$I_S = -1\text{A}, V_{GS}=0\text{V}$		-0.76	-1	V
I_S	Maximum Body-Diode Continuous Current				-2	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS} = -20\text{V}, f=1\text{MHz}$		1500	2600	pF
C_{oss}	Output Capacitance			200		pF
C_{rss}	Reverse Transfer Capacitance			150		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		10		Ω
SWITCHING PARAMETERS						
$Q_g(-10\text{V})$	Total Gate Charge	$V_{GS} = -10\text{V}, V_{DS} = -20\text{V}, I_D = -30\text{A}$		16.2	21	nC
$Q_g(-4.5\text{V})$	Total Gate Charge			7.2	9.4	nC
Q_{gs}	Gate Source Charge			3.8		nC
Q_{gd}	Gate Drain Charge			3.5		nC
$t_{D(\text{on})}$	Turn-On DelayTime	$V_{GS} = -10\text{V}, V_{DS} = -20\text{V}, R_L = 1.4\Omega, R_{\text{GEN}} = 3\Omega$		6.2		ns
t_r	Turn-On Rise Time			8.4		ns
$t_{D(\text{off})}$	Turn-Off DelayTime			44.8		ns
t_f	Turn-Off Fall Time			41.2		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F = -12\text{A}, dI/dt = 100\text{A}/\mu\text{s}$		21	27	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F = -12\text{A}, dI/dt = 100\text{A}/\mu\text{s}$		14		nC

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: P-CHANNEL

Fig 12: On-Region Characteristics

Figure 13: Transfer Characteristics

Figure 14: On-Resistance vs. Drain Current and Gate Voltage

Figure 15: On-Resistance vs. Junction Temperature

Figure 16: On-Resistance vs. Gate-Source Voltage

Figure 17: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: P-CHANNEL

Figure 18: Gate-Charge Characteristics

Figure 19: Capacitance Characteristics

Figure 20: Maximum Forward Biased Safe Operating Area (Note E)

Figure 21: Single Pulse Power Rating Junction-to-Ambient (Note E)

Figure 22: Normalized Maximum Transient Thermal Impedance